

**FEATURES**

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- Fast switching for high efficiency
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

**APPLICATIONS**

For use in high efficient switching rectification of power supply, inverters, converters, and freewheeling diodes for consumer and telecommunication

**MECHANICAL DATA**

- **Package:** SOD-123FL  
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

**MAXIMUM RATINGS** (T<sub>a</sub>=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	H1A	H1B	H1D	H1G	H1J	H1K	H1M
Device marking code			H1A	H1B	H1D	H1G	H1J	H1K	H1M
Repetitive peak reverse voltage	VRRM	V	50	100	200	400	600	800	1000
Average rectified output current @60Hz Half-sine wave, Resistance load, T <sub>a</sub> (FIG.1)	I <sub>O</sub>	A	1.0						
Surge(non-repetitive)forward current @60Hz half-sine wave, 1 cycle, T <sub>j</sub> =25°C	I <sub>FSM</sub>	A	30						
Storage temperature	T <sub>stg</sub>	°C	-55 ~+150						
Junction temperature	T <sub>j</sub>	°C	-55 ~+150						

**ELECTRICAL CHARACTERISTICS** (T<sub>a</sub>=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	H1A	H1B	H1D	H1G	H1J	H1K	H1M
Maximum instantaneous forward voltage drop per diode	V <sub>F</sub>	V	I <sub>FM</sub> =1.0A	1.0			1.3	1.7		
Maximum reverse recovery time	t <sub>rr</sub>	ns	I <sub>F</sub> =0.5A, I <sub>R</sub> =1.0A, I <sub>RR</sub> =0.25A	50				75		
Maximum DC reverse current at rated DC blocking voltage per diode	I <sub>RRM</sub>	µA	T <sub>a</sub> =25°C	5						
			T <sub>a</sub> =125°C	100						

**THERMAL CHARACTERISTICS** (T<sub>a</sub>=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	H1A	H1B	H1D	H1G	H1J	H1K	H1M
Thermal resistance	R <sub>θJ-A</sub>	°C/W	70 <sup>1)</sup>						
	R <sub>θJ-L</sub>		20 <sup>1)</sup>						

Note (1) Thermal resistance between junction and ambient and between junction and lead mounted on P.C.B with 3mm\*3mm copper pad areas.

**CHARACTERISTICS (TYPICAL)**

FIG.1: Io-TL Cure

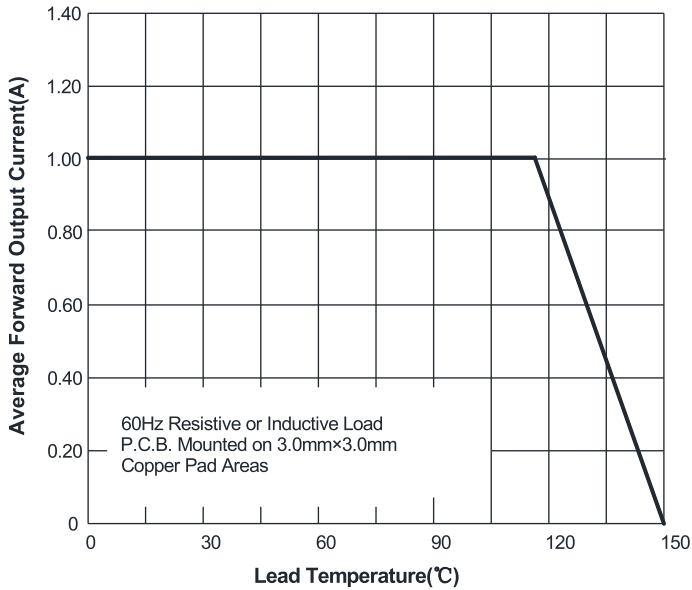


FIG.2: Forward Surge Current Capability

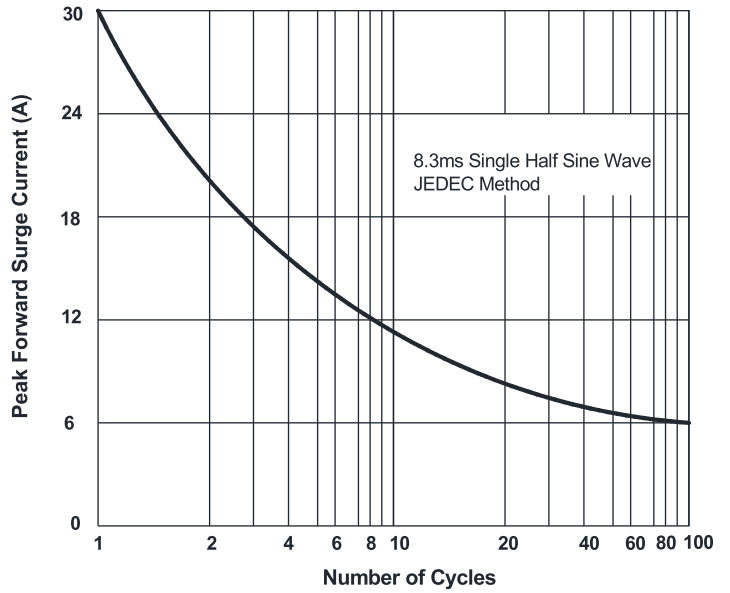


FIG.3: Typical Forward Characteristics

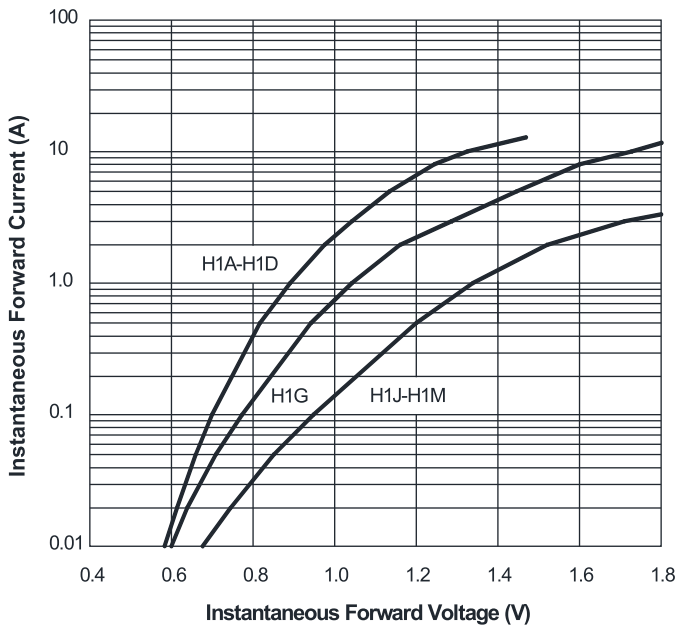


FIG.4: Typical Reverse Characteristics

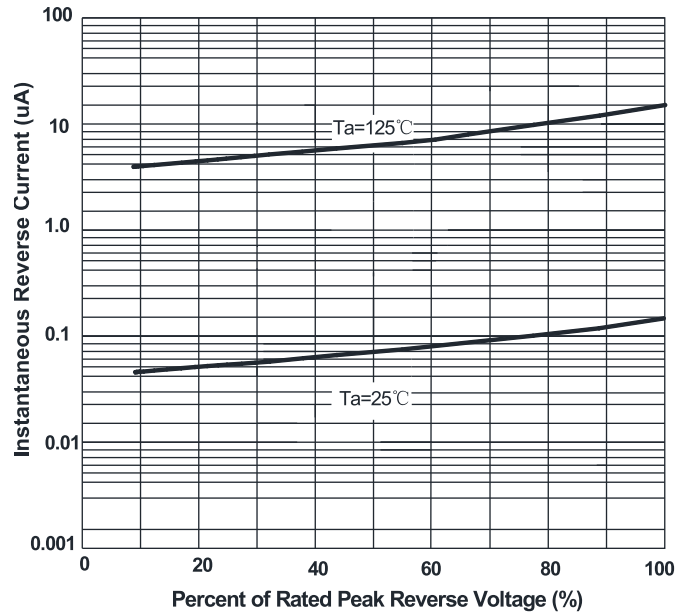
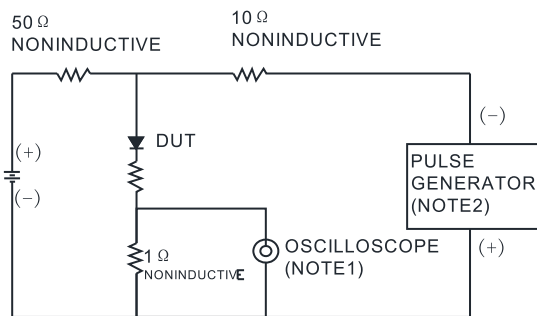
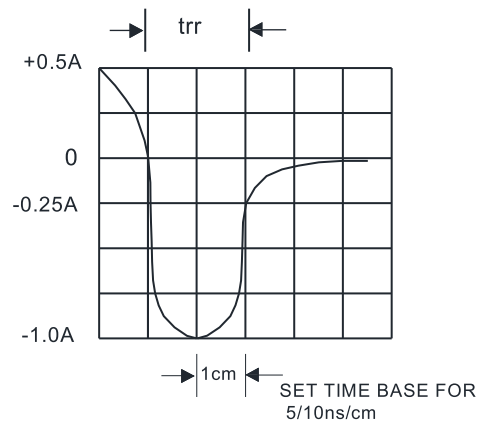


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time



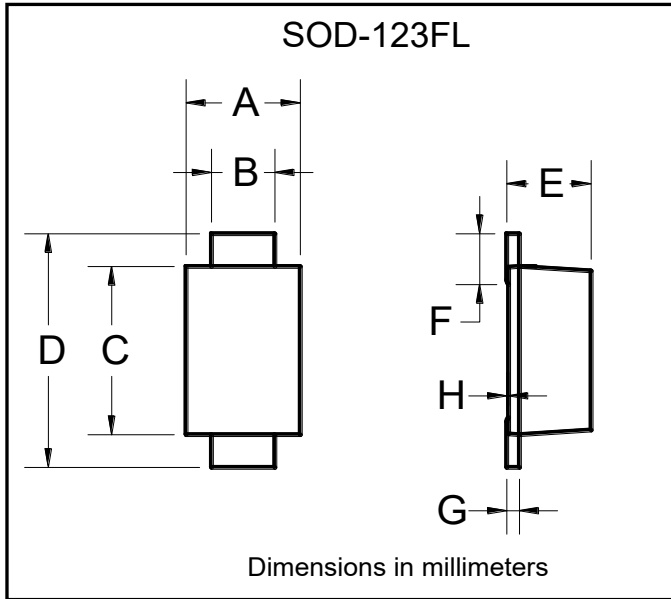
NOTES:  
1. Rise Time=7ns max .Input Impedance=1MΩ 22pf  
2. Rise Time=10ns max. Source Impedance=50Ω



**PACKAGING INFORMATION**

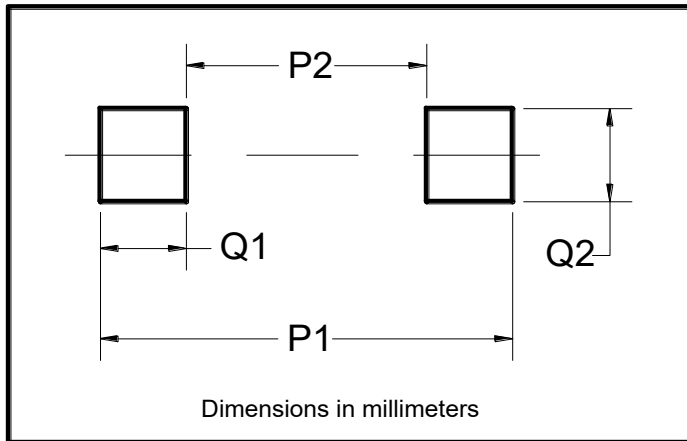
PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
H1A THRU H1M	X07	Approximate 0.0169	3000	15000	120000	7" reel
H1A THRU H1M	Omit for Standard	Approximate 0.0169	10000	30000	210000	13" reel

**OUTLINE DIMENSIONS**



SOD-123FL		
Dim	Min	Max
A	1.60	1.90
B	0.90	1.10
C	2.55	2.85
D	3.60	3.90
E	1.00	1.20
F	0.40	0.90
G	0.10	0.25
H	0.02	0.05

**SUGGESTED PAD LAYOUT**



SOD-123FL	
Dim	Millimeters
P1	3.90
P2	1.90
Q1	1.00
Q2	1.50